











July 25, 2024 Ballroom, Level 7, Hotel Olive Tree, Penang

Time	Program
9:45 AM	Arrival of Chief Guest
10:00 – 11:40 AM	Inaugural Session
	Welcome: David Bergman, Vice President (Standards & Technology) - IPC
	Keynote: Dr John W Mitchell, President & CEO - IPC
	Topic: What's New in Tech: The Micro Trends Defining the Future of Electronics
	Chief Guest Address: HE YB Jagadeep Singh Deo,
	Deputy Chief Minister II, Govt of Penang, Malaysia
	Felicitating Partner Malaysian organizations (PSDC, SHRDC, Invest Penang, MICCI, IEEE, TEEAM, MCCI, SAMENTA, FMM, MATRADE)
11:40 – 1:00 PM	Panel Session: Advanced Packaging of Semiconductor: The need to Build an Industrial Eco System
	Introduction & Session Moderator: David Bergman, Vice President
	(Standards & Technology) - IPC
	Presentation Topic: Advanced packaging: Frontier of semiconductor technology
	Speaker: Teng Chow Ooi, Sr Director Program Office - Intel Corporation
	Presentation Topic: Advanced Packaging/Substrate Materials and Open Innovation
	Platform
	Speaker: Takatoshi Ikeuchi, Electronics R&D Center - Resonac Corporation
	(Japan Semiconductor Packaging Consortium)
	Q&A
1:00 - 2:00 PM	Networking Lunch
2:00 – 3:30 PM	Panel Discussion: Importance of Advanced Packaging Technology
	@ Semiconductor & Electronics Industry
	Session Moderator: Ir Dr Bernard Lim, Chair – Elect, IEEE Malaysia & Chief Operating Office
	Appscard Global Research & Innovation Center
	Panel Members:
	Dr. Eu Poh Leng, Senior Director of External Package Innovation, Chief Technology
	Office - NXP Semiconductors
	Ang Wee Seng, Executive Director - Singapore Semiconductor Industry Association
	Earl Lawrence S. Qua, President - Electronics Industries Association of Philippines
	Anurag Awasthi, Vice President - India Electronics & Semiconductor Association
	Dr Hari Narayanan, CEO - Penang Skills Development Centre
	Ayman Ahmed, CEO Pearl Semiconductor - Global Semiconductor Alliance, Egypt
	Do Thi Thuy Huong, Board Director - Vietnam Electronics Industries Association